IPC ASSOCIATION ELECTRONIC	Material Com © Copyright 2005. international and P	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
uppliei	r Information														
Company name* Company to				unique ID			Unique ID Authority				Response Date*				
onsemi												2025-06-07			
ontact N	ame	Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-I	Env-Stewards		Product Enviro Compliance]	NA					Product-Env-Stewards@onsemi.com			
uthorize	d Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
roduct-I	Env-Stewards	Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr I		tem Number Mfr Item Name				Effective Date Version Manufacturing S		ng Site	V	/eight*	UOM	Unit Type		
		BD135G BIP C77 NPN 1.52		A 45V		2025-06-07 CNG			6	01.02	mg	Each			
lanufa	cturing Process Inform Terminal Plating / Grid Array N		Terminal Base	Alloy	-STD-020 MS	I. Poting	Dank Proc	ess Rody	Tamparatu	ra May Tim	a at Daak	Tamparatu	ra Numb	er of Reflow Cyc	plac
	8 - 1 mg ma m		CU Allov NA			L Kanng	Peak Process Body Temperature N		30	ic at i cak	seconds 3		er of Kerlow Cyc	Lies	
omments	` ′		COTINO		11.1					150		Second	.5 5		
omments	1														
r more	information regarding materia	al composition	nlease refer to	n nage 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall apply and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.01	mg	Supplier	Silicon (Si)	7440-21-3		6.01	mg
Die Attach Solder	0.29		Supplier	Silver (Ag)	7440-22-4		0.0072	mg
			A	Lead (Pb)	7439-92-1	7a	0.2682	mg
			Supplier	Tin (Sn)	7440-31-5		0.0145	mg
Lead Frame	315.4	mg	Supplier	Zinc (Zn)	7440-66-6		0.3154	mg
			Supplier	Iron (Fe)	7439-89-6		0.3154	mg
			Supplier	Copper (Cu)	7440-50-8		314.7692	mg
Mold Compound-Black	268.29			Phenolic Resin	proprietary data		16.0974	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		26.829	mg
			Supplier	Carbon Black (C)	1333-86-4		1.3414	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		20.1218	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		203.9004	mg
Plating	8.02	mg	Supplier	Tin (Sn)	7440-31-5		8.02	mg
Wire Bond - Al	3.01	mg	Supplier	Aluminum (Al)	7429-90-5		3.01	mg